Abstract of the invention

In a method for structuring the surface of a substrate (1), a prepares substrate (1) is elastically expanded by the application of a tensile stress so that a surface area of the substrate (1) in which a structure is to be created, is enlarged. Then, in the surface area, a structure is produced that is larger than the structure to be produced. For this purpose at least one solution is applied to the substrate 1, which solvent contains at least one solid substance dissolved in a solvent. The solvent is then removed from the surface of the substrate 1 so that the solid substance remains behind. The expansion of the substrate (1) is at least partly reversed by the reduction or removal of the tensile stress so that the size of the structure (1) is reduced to the size of the structure (1) to be produced. In the material of the substrate (1), a compression stress can also be created to reduce the size of the structure to the size of the structure to be produced.

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